

# MECHANICAL CASE OUTLINE

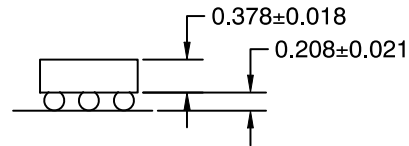
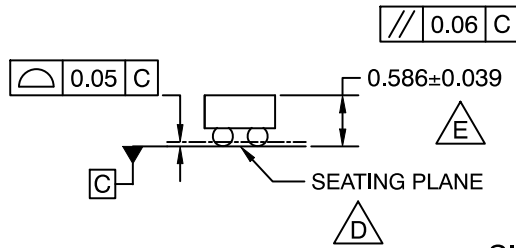
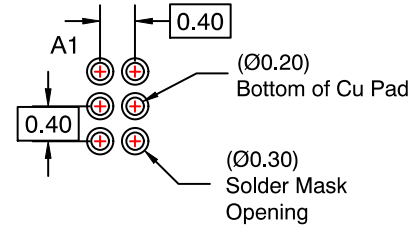
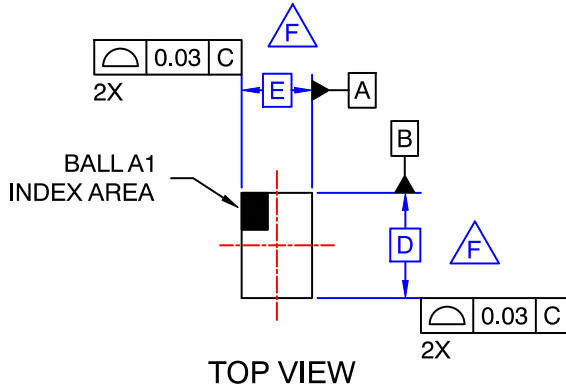
## PACKAGE DIMENSIONS

ON Semiconductor®



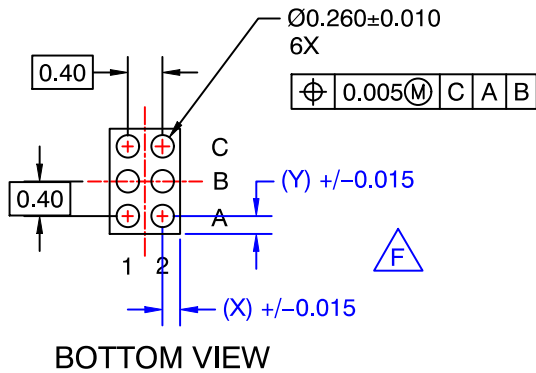
WLCSP6 1.37x0.97x0.586  
CASE 567RR  
ISSUE O

DATE 30 NOV 2016



### NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASMEY14.5M, 2009.
- D. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE TYPICAL HEIGHT IS 586 MICRONS ±39 MICRONS (547–625 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y, SEE PRODUCT DATASHEET.



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| <b>DESCRIPTION:</b>     | <b>WLCSP6 1.37x0.97x0.586</b> | <b>PAGE 1 OF 1</b>   |

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